Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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FAIRCHILD SEMICONDUCTOR®

December 2007

FGA70N30T
300V, 70A PDP IGBT

Features

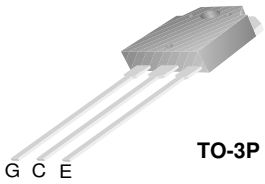
- High current capability
- Low saturation voltage: $V_{CE(sat)}$ =1.5V @ I_C = 40A
- High input impedance
- Fast switching
- RoHS complaint

Application

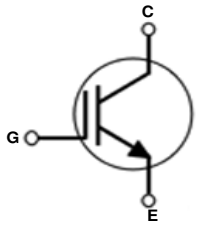
. PDP System

General Description

Using Novel Trench IGBT Technology, Fairchild's new sesries of trench IGBTs offer the optimum performance for PDP applications where low conduction and switching losses are essential.



TO-3P



Absolute Maximum Ratings

Symbol	Description		Ratings	Units
V_{CES}	Collector-Emitter Voltage		300	V
V_{GES}	Gate-Emitter Voltage		±30	V
$I_{C\ pulse(1)*}$	Pulsed Collector Current	@ T_C = 25°C	160	A
P_D	Maximum Power Dissipation	@ T_C = 25°C	201	W
	Maximum Power Dissipation	@ T_C = 100°C	90.6	W
T_J	Operating Junction Temperature		-55 to +150	°C
T_{stg}	Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$(IGBT)	Thermal Resistance, Junction-to-Case	--	0.62	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	40	°C/W

Notes:

(1)Repetitive test , pluse width = 100usec , Duty = 0.2

* Ic_pluse limited by max Tj

Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Type	Qty per Tube	Max Qty per Box
FGA70N30T	FGA70N30TTU	TO-3P	Tube	30ea	-

Electrical Characteristics $T_C = 25^oC$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV_{CES}	Collector-Emitter Breakdown Voltage	V_{GE} = 0V, I_C = 250uA	300	--	--	V
$\Delta B_{VCES}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	V_{GE} = 0V, I_C = 250uA	--	0.2	--	V/^{o}C
I_{CES}	Collector Cut-Off Current	V_{CE} = V_{CES}, V_{GE} = 0V	--	--	250	uA
I_{GES}	G-E Leakage Current	V_{GE} = V_{GES}, V_{CE} = 0V	--	--	± 400	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	I_C = 250uA, V_{CE} = V_{GE}	3.0	4.5	5.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C =20A, V_{GE} = 15V	--	1.2	1.5	V
		I_C =40A, V_{GE} = 15V	--	1.5	--	V
		I_C =70A, V_{GE} = 15V T_C = 25^{o}C	--	1.8	--	V
		I_C = 70A, V_{GE} = 15V T_C = 125^{o}C	--	1.9	--	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	V_{CE} = 30V, V_{GE} = 0V f = 1MHz	--	3000	--	pF
C_{oes}	Output Capacitance		--	160	--	pF
C_{res}	Reverse Transfer Capacitance		--	110	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 200V, I_C = 40A R_G = 15Ω, V_{GE} = 15V Resistive Load, T_C = 25^{o}C	--	32	--	ns
t_r	Rise Time		--	90	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	175	--	ns
t_f	Fall Time		--	170	300	ns
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 200V, I_C = 40A R_G = 15Ω, V_{GE} = 15V Resistive Load, T_C = 125^{o}C	--	30	--	ns
t_r	Rise Time		--	90	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	185	--	ns
t_f	Fall Time		--	235	--	ns
Q_g	Total Gate Charge	V_{CE} = 200V, I_C = 40A V_{GE} = 15V	--	125	--	nC
Q_{ge}	Gate-Emitter Charge		--	25	--	nC
Q_{gc}	Gate-Collector Charge		--	55	--	nC

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

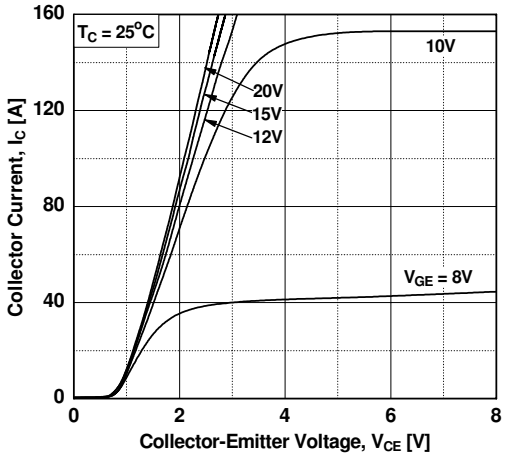


Figure 2. Typical Output Characteristics

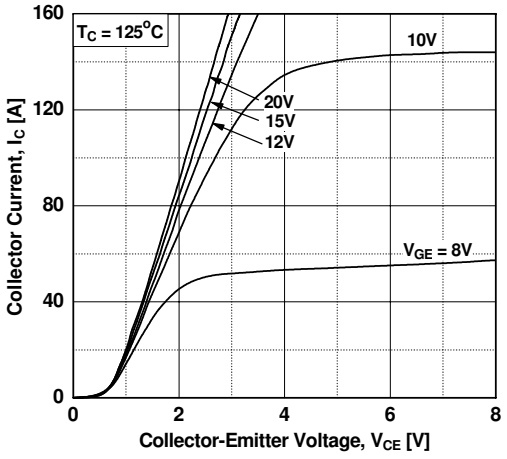


Figure 3. Typical Saturation Voltage Characteristics

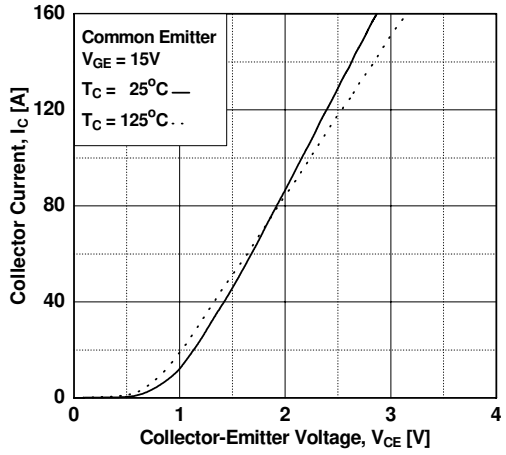


Figure 4. Transfer Characteristics

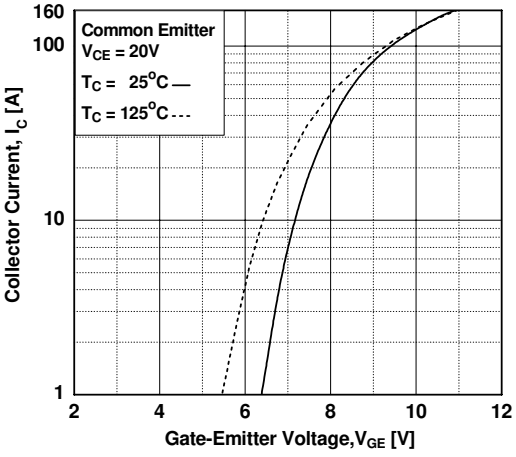


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

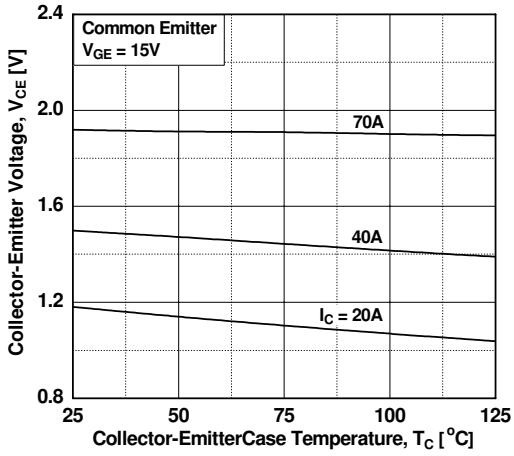
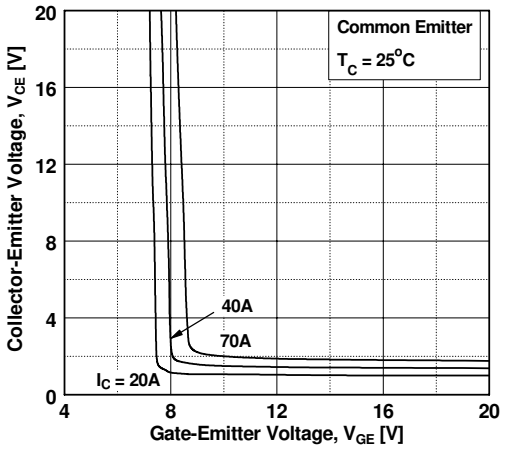


Figure 6. Saturation Voltage vs. V_{GE}



Typical Performance Characteristics (Continued)

Figure 7. Saturation Voltage vs. V_{GE}

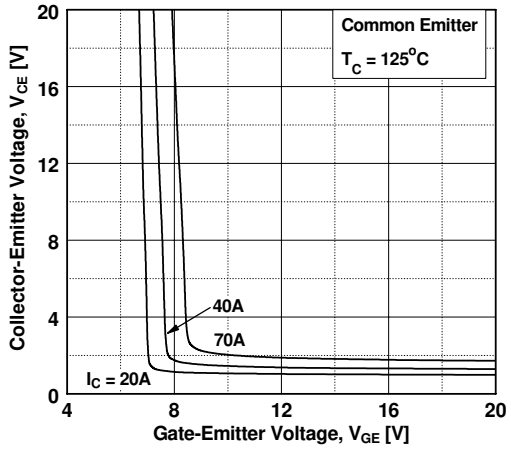


Figure 8. Capacitance Characteristics

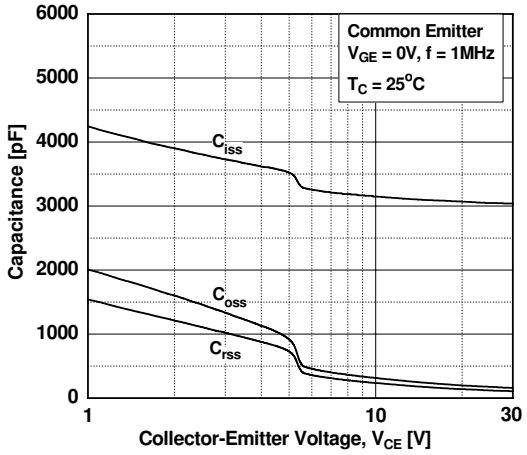


Figure 9. Gate Charge Characteristics

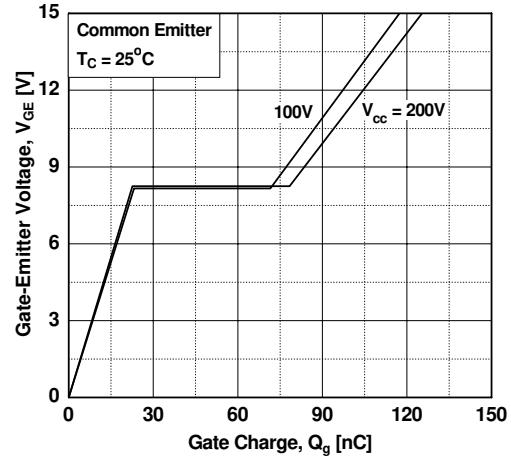


Figure 10. SOA Characteristics

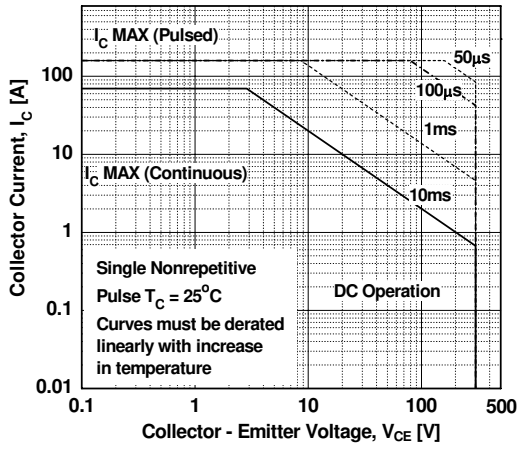


Figure 11. Turn-on Characteristics vs. Gate Resistance

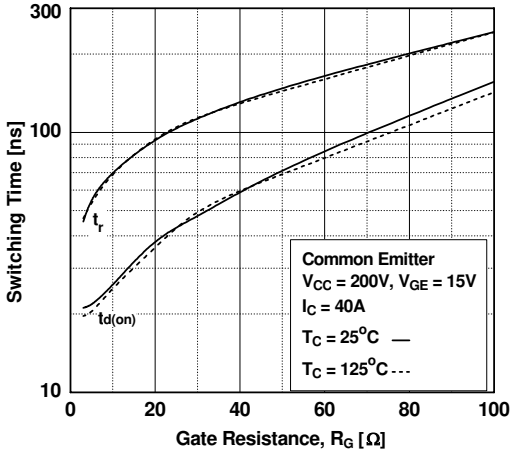
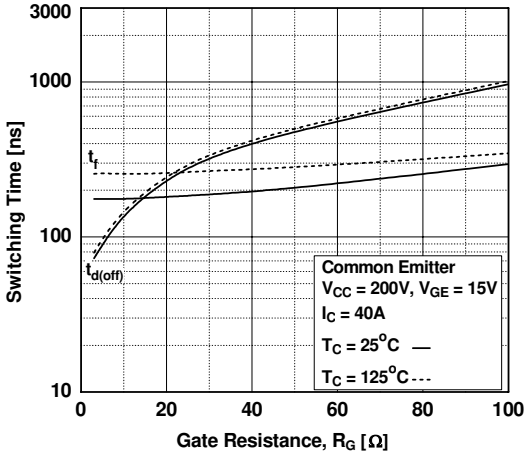


Figure 12. Turn-off Characteristics vs. Gate Resistance



Typical Performance Characteristics (Continued)

Figure 13. Turn-on Characteristics vs. Collector Current

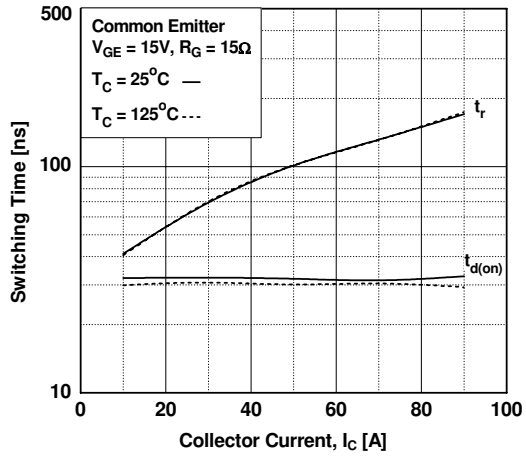


Figure 14. Turn-off Characteristics vs. Collector Current

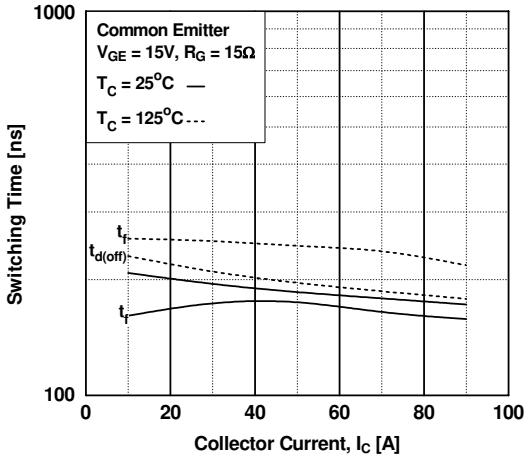


Figure 15. Switching Loss vs. Gate Resistance

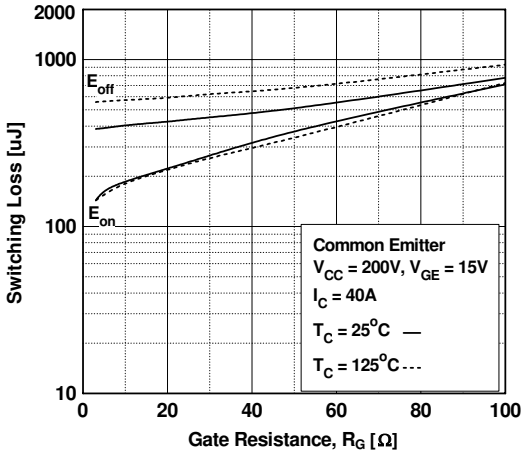


Figure 16. Switching Loss vs. Collector Current

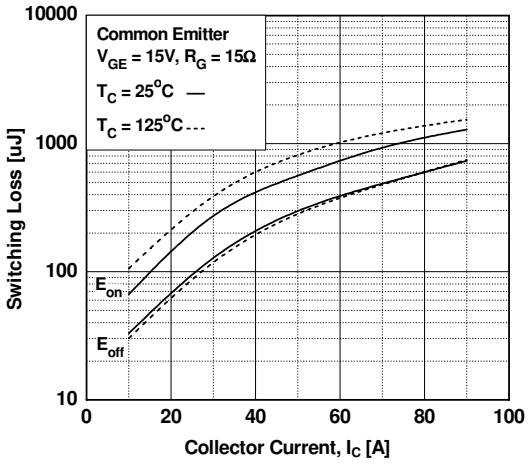
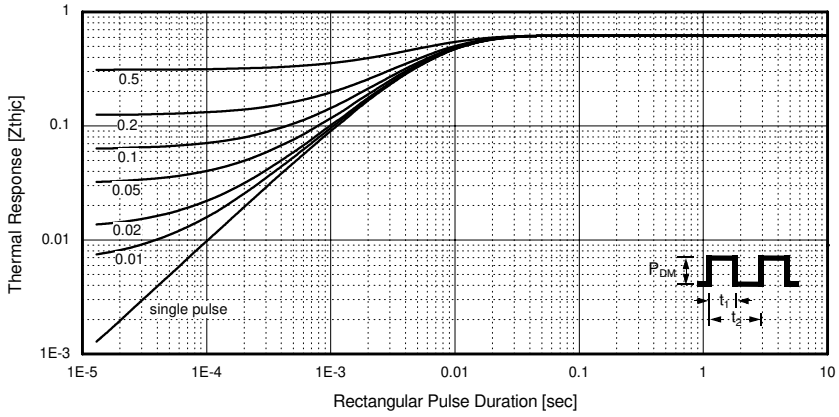
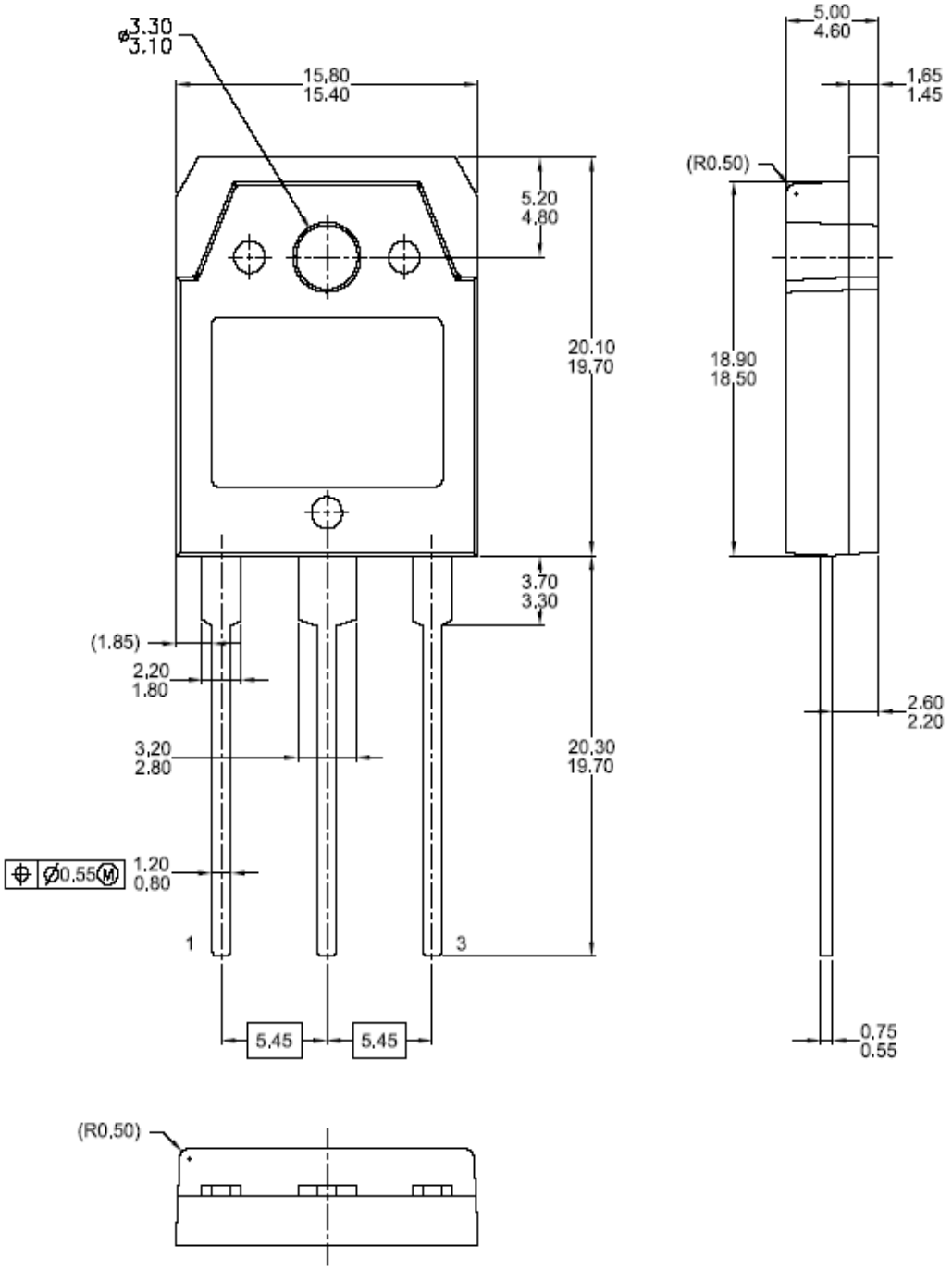


Figure 17. Transient Thermal Impedance of IGBT



TO-3PN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15.80
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(R0.50)

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